

Title (en)
METHOD FOR CONNECTING A SUBSTRATE ARRANGEMENT TO AN ELECTRONIC COMPONENT USING A PREFIXATION AGENT APPLIED ONTO A CONTRACTING MATERIAL LAYER, CORRESPONDING SUBSTRATE ARRANGEMENT, AND METHOD FOR PRODUCING SAME

Title (de)
VERFAHREN ZUM VERBINDEN EINER SUBSTRATANORDNUNG MIT EINEM ELEKTRONIKBAUTEIL MIT VERWENDUNG EINES AUF EINE KONTAKTIERUNGSMATERIALSCHICHT AUFGEBRACHTEN VORFIXIERMITTELS, ENTSPRECHENDE SUBSTRATANORDNUNG UND VERFAHREN ZU IHREM HERSTELLEN

Title (fr)
PROCÉDÉ DE FABRICATION D'UN ENSEMBLE SUBSTRAT, ENSEMBLE SUBSTRAT ET PROCÉDÉ DE LIAISON D'UN ENSEMBLE SUBSTRAT AVEC UN COMPOSANT ÉLECTRONIQUE

Publication
EP 3360154 A2 20180815 (DE)

Application
EP 16777954 A 20160928

Priority
• EP 15188966 A 20151008
• EP 2016073102 W 20160928

Abstract (en)
[origin: WO2017060140A2] The invention relates to a method for producing a substrate arrangement (10; 10'; 10'') for connecting to an electronic component (30; 30''), comprising the steps of: - providing a substrate (11) having a first side (12) and a second side (13), - applying a contacting material layer (15) to the first side (12) of said substrate (11), and - applying a pre-fixation agent (18) to at least some sections of a side (16) of the contacting material layer (15) that faces away from said substrate (11).

IPC 8 full level
H01L 21/48 (2006.01); **H01L 21/58** (2006.01); **H01L 21/60** (2006.01); **H01L 21/683** (2006.01); **H01L 23/14** (2006.01); **H01L 23/373** (2006.01); **H01L 23/488** (2006.01); **H01L 23/495** (2006.01); **H05K 3/32** (2006.01); **H05K 3/34** (2006.01); **H05K 3/36** (2006.01)

CPC (source: EP KR US)
H01L 21/4821 (2013.01 - EP KR US); **H01L 21/4867** (2013.01 - EP KR US); **H01L 21/4871** (2013.01 - KR US); **H01L 21/6836** (2013.01 - EP KR US); **H01L 23/142** (2013.01 - EP KR US); **H01L 23/3735** (2013.01 - EP KR US); **H01L 23/49582** (2013.01 - EP KR US); **H01L 24/27** (2013.01 - EP KR US); **H01L 24/29** (2013.01 - EP KR US); **H01L 24/83** (2013.01 - EP KR US); **H01L 24/95** (2013.01 - EP US); **H05K 3/303** (2013.01 - EP); **H05K 3/3436** (2013.01 - KR US); **H01L 24/75** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 2221/68331** (2013.01 - EP US); **H01L 2221/68363** (2013.01 - EP US); **H01L 2221/68368** (2013.01 - EP US); **H01L 2221/68381** (2013.01 - EP US); **H01L 2224/2731** (2013.01 - EP US); **H01L 2224/27312** (2013.01 - EP US); **H01L 2224/27318** (2013.01 - EP US); **H01L 2224/2732** (2013.01 - EP US); **H01L 2224/27334** (2013.01 - EP US); **H01L 2224/27418** (2013.01 - EP US); **H01L 2224/2744** (2013.01 - EP US); **H01L 2224/27848** (2013.01 - EP US); **H01L 2224/2919** (2013.01 - EP US); **H01L 2224/29294** (2013.01 - EP US); **H01L 2224/293** (2013.01 - EP US); **H01L 2224/29339** (2013.01 - EP US); **H01L 2224/2939** (2013.01 - EP US); **H01L 2224/75272** (2013.01 - EP US); **H01L 2224/753** (2013.01 - EP US); **H01L 2224/83002** (2013.01 - EP US); **H01L 2224/83192** (2013.01 - EP US); **H01L 2224/83439** (2013.01 - EP US); **H01L 2224/83444** (2013.01 - EP US); **H01L 2224/83801** (2013.01 - EP US); **H01L 2224/8384** (2013.01 - EP US); **H01L 2224/8385** (2013.01 - EP US); **H01L 2224/83898** (2013.01 - EP US); **H01L 2224/83907** (2013.01 - EP US); **H01L 2224/83986** (2013.01 - EP US); **H01L 2224/95** (2013.01 - EP US); **H01L 2224/97** (2013.01 - EP US); **H05K 3/305** (2013.01 - EP US); **H05K 3/321** (2013.01 - EP); **H05K 3/3436** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP US)

Citation (search report)
See references of WO 2017060140A2

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 3154079 A1 20170412; CN 108604555 A 20180928; CN 108604555 B 20220308; EP 3360154 A2 20180815; EP 3940758 A2 20220119; EP 3940758 A3 20220810; JP 2018530166 A 20181011; JP 6664751 B2 20200313; KR 102085191 B1 20200305; KR 20180059913 A 20180605; TW 201724295 A 20170701; TW 201909292 A 20190301; TW I652744 B 20190301; TW I709180 B 20201101; US 10622331 B2 20200414; US 2018286831 A1 20181004; WO 2017060140 A2 20170413; WO 2017060140 A3 20170601

DOCDB simple family (application)
EP 15188966 A 20151008; CN 201680059144 A 20160928; EP 16777954 A 20160928; EP 2016073102 W 20160928; EP 21177341 A 20160928; JP 2018517696 A 20160928; KR 20187012302 A 20160928; TW 105132378 A 20161006; TW 107142487 A 20161006; US 201615766234 A 20160928